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Form 1449 (Modified) Information Disclosure Statement By Applicant (Use Several Sheets if Necessary)	Atty Docket No. NSC1P131X1/P04314P01	Application No.: Unassigned
	Applicant: Nguyen et al. Filing Date Herewith	Group Unassigned

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U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
DF	A	6,121,689	09/00	Capote et al.			
DF	B	6,063,647	05/00	Chen et al.			
DP	C	6,060,373	05/00	Saitoh			
DF	D	5,895,976	04/00	Morrell et al.			
DF	E	5,953,623	09/99	Boyko et al.			
DF	F	5,668,059	09/97	Christie et al.			
DF	G	6,071,757	06/00	Fogal et al.			
DF	H	6,245,595	06/01	Nguyen et al.			
	I						

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	J							
	K							
	L							
	M							
	N							

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
DP	O	Kulicke & Soffa, "Flip Chip Division, Polymer Collar Wafer Level Package; Achieve Maximum Reliability for Wafer Level Packages!", December 7, 2001, www.kns.com
DF	P	Kulicke & Soffa, "Flip Chip Division, Polymer Collar Wafer Level Package; See the Polymer Collar WLP difference!", December 7, 2001, www.kns.com
	Q	
Examiner <i>Don Jha</i>		Date Considered 3/8/03

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.